

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

Applicant : Glenn J. Leedy
Filed : Concurrently Herewith
As a Division of
Application No. : 09/607,363
Filed : June 30, 2000
For : THREE DIMENSIONAL STRUCTURE INTEGRATED
CIRCUIT FABRICATION PROCESS (AS
AMENDED)

New York, New York 10020
July 3, 2003

Hon. Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

PRELIMINARY AMENDMENT

Sir:

Preliminary to examination, applicant hereby amends
the above-identified patent application as follows:

In the Title

Please amend the title from "THREE DIMENSIONAL
STRUCTURE INTEGRATED CIRCUIT FABRICATION PROCESS" to -- THREE
DIMENSIONAL STRUCTURE INTEGRATED CIRCUIT --.